L	Hits	Search Text	DB	Time stamp
Number		438/15,687,683,762,763.ccls. and	USPAT;	2004/03/15
1	3	(integrated adj circuit) and (contact adj	US-PGPUB;	15:10
		pad) and ((under adj bump adj metallurgy)	EPO; JPO;	
, l		or ubm) and (solder) and (wire) and	DERWENT	
_ <b> </b>		(barrier)		0004/02/25
2	10	257/737,738,613,761.ccls. and (integrated	USPAT; US-PGPUB;	2004/03/15 15:12
		adj circuit) and (contact adj pad) and ((under adj bump adj metallurgy) or ubm)	EPO; JPO;	15.12
		and (solder) and (wire) and (barrier)	DERWENT	
_	6039	(integrated adj circuit) and (contact adj	USPAT;	2003/01/30
		pad) and (under adj bump adj region or	US-PGPUB;	15:08
		layer)	EPO; JPO;	
	^	(3tt. a) - 34 - 244t\ - 24 - 144t\	DERWENT	2003/01/30
-	0	(integrated adj circuit) and (contact adj pad) and (under adj bump adj region or	USPAT; US-PGPUB;	15:10
		layer) and (solder adj bonds) and (wire	EPO; JPO;	20.20
		adj bomds)	DERWENT	
-	184	(integrated adj circuit) and (contact or	USPAT;	2003/01/30
		output/input adj pads) and (under adj	US-PGPUB;	15:15
		bump adj region or layer) and (solder adj	EPO; JPO;	
_	118	bonds) and (wire adj bonds) (integrated adj circuit) and (contact adj	DERWENT USPAT;	2003/01/31
	110	pad) and (under adj bump adj region or	US-PGPUB;	10:15
		layer) and (solder adj bonds) and (wire	EPO; JPO;	
		adj bonds)	DERWENT	
-	118	(integrated adj circuit) and (contact adj	USPAT;	2003/01/31
]		pad) and (under adj bump adj region or	US-PGPUB; EPO; JPO;	10:25
		layer) and (solder adj bonds) and (wire adj bonds) and (barrier adj region or	DERWENT	
		layer) and (passivation adj region or		
		layer)		
-	0	"09888674" and (barrier)	USPAT;	2003/06/19
		,	US-PGPUB;	15:37
			EPO; JPO;   DERWENT	
_	o	"09888674" and (barrier)	USPAT;	2003/06/20
		( <del></del> (	US-PGPUB;	10:14
			EPO; JPO;	
			DERWENT	2002/01/21
-	0	"09/888674" and (barrier)	USPAT; US-PGPUB;	2003/01/31   11:45
			EPO; JPO;	11.30
			DERWENT	
-	118		USPAT;	2003/07/07
		pad) and (under adj bump adj region or	US-PGPUB;	09:59
		layer) and (solder adj bonds) and (wire	EPO; JPO;	]
		adj bonds) and (barrier adj region or layer) and (passivation adj region or	DERWENT	
		layer) and (passivation adj region of		
_	0	(integrated adj circuit) and (contact adj	USPAT;	2003/01/31
		pad) and ((under adj bump adj metallurgy)	US-PGPUB;	12:24
		or ubm) and (solder adj bonds) and (wire	EPO; JPO;	
		adj bonds) and (barrier) and	DERWENT	
	0	<pre>(passivation) (integrated adj circuit) and (contact adj</pre>	USPAT;	2003/01/31
-		pad) and ((under ad) bump ad) metallurgy)	US-PGPUB;	12:25
[		or ubm) and (solder adj bonds) and (wire	EPO; JPO;	
		adj bonds) and (barrier)	DERWENT	
-	4	(integrated adj circuit) and (contact adj	USPAT;	2003/01/31
		<pre>pad) and ((under adj bump adj metallurgy) or ubm) and (solder) and (wire adj bonds)</pre>	US-PGPUB; EPO; JPO;	12:26
		and (barrier)	DERWENT	
_	28	(integrated adj circuit) and (contact adj	USPAT;	2003/02/01
		pad) and ((under adj bump adj metallurgy)	US-PGPUB;	15:10
		or ubm) and (solder) and (wire) and	EPO; JPO;	
L		(barrier)	DERWENT	

-	118	(integrated adj circuit) and (contact adj pad) and (under adj bump adj region or	USPAT; US-PGPUB;	2003/01/31 15:38
		layer) and (solder adj bonds) and (wire adj bonds) and (barrier adj region or	EPO; JPO; DERWENT	13.30
		layer) and (passivation adj region or layer)	DERWENT	
-	23	(integrated adj circuit) and (contact adj	USPAT; US-PGPUB;	2003/07/07 10:03
		<pre>pad) and ((under adj bump adj metallurgy) or ubm) and (solder) and (wire) and</pre>	EPO; JPO;	10.03
-	. 0	<pre>(barrier) and (lead) 438/15.ccls. and (integrated adj circuit)</pre>	DERWENT USPAT;	2003/05/30
		and (contact adj pad) and ((under adj bump adj metallurgy) or ubm) and (solder)	US-PGPUB; EPO; JPO;	18:38
-	0	and (wire) and (barrier) 438/15,762,763.ccls. and (integrated adj	DERWENT USPAT;	2004/03/15
	,	circuit) and (contact adj pad) and ((under adj bump adj metallurgy) or ubm)	US-PGPUB; EPO; JPO;	15:09
_	4	and (solder) and (wire) and (barrier) 257/737.ccls. and (integrated adj	DERWENT USPAT;	2004/03/15
		circuit) and (contact adj pad) and ((under adj bump adj metallurgy) or ubm)	US-PGPUB; EPO; JPO;	15:11
	27	and (solder) and (wire) and (barrier) (integrated adj circuit) and (contact adj	DERWENT USPAT;	2003/05/30
		pad) and ((under adj bump adj metallurgy) or ubm) and (solder) and (wire) and	US-PGPUB; EPO; JPO;	18:01
	0	(barrier) and (lead) 438/15.ccls. and (integrated adj circuit)	DERWENT USPAT;	2003/05/30
_		and (contact adj pad) and ((under adj bump adj metallurgy) or ubm) and (solder)	US-PGPUB; EPO; JPO;	18:44
	100	and (wire) and (barrier)	DERWENT	2003/05/30
_	123	(integrated adj circuit) and (contact adj pad) and (under adj bump adj region or	USPAT; US-PGPUB;	18:41
		layer) and (solder adj bonds) and (wire adj bonds) and (barrier adj region or	EPO; JPO; DERWENT	
		layer) and (passivation adj region or layer)	HCDAM.	2003/05/30
_	4	257/737.ccls. and (integrated adj circuit) and (contact adj pad) and	USPAT; US-PGPUB; EPO; JPO;	18:51
		((under adj bump adj metallurgy) or ubm) and (solder) and (wire) and (barrier)	DERWENT USPAT;	2003/05/30
_		438/15.ccls. and (integrated adj circuit) and (contact adj pad) and ((under adj	US-PGPUB; EPO; JPO;	18:45
		bump adj metallurgy) or ubm) and (solder) and (wire) and (barrier)	DERWENT	2002/05/20
-	8	257/738.ccls. and (integrated adj circuit) and (contact adj pad) and	USPAT; US-PGPUB;	2003/05/30 19:03
		((under adj bump adj metallurgy) or ubm) and (solder) and (wire) and (barrier)	EPO; JPO; DERWENT	2002/05/20
-	4	circuit) and (contact adj pad) and	USPAT; US-PGPUB;	2003/05/30 19:04
		((under adj bump adj metallurgy) or ubm) and (solder) and (wire) and (barrier)	EPO; JPO; DERWENT	2002/05/21
-	36	pad) and (barrier adj layer) and (nickel	USPAT; US-PGPUB;	2003/05/31 11:42
		adj barrier) and (solder adg layer)	EPO; JPO; DERWENT	0000/05/03
-	4	(integrated adj circuit) and (contact adj pad) and (barrier adj layer) and (nickel	USPAT; US-PGPUB;	2003/05/31 11:43
		adj barrier) and (solder adj layer)	EPO; JPO; DERWENT	0000/06/10
-	0	"6221682" and gold	USPAT; US-PGPUB;	2003/06/19 13:21
			EPO; JPO; DERWENT	2002/12/22
-	0	"20010011764" and gold	USPAT; US-PGPUB;	2003/12/02 18:25
			EPO; JPO; DERWENT	0000 (05 (15
-	2	"20010011764"	USPAT; US-PGPUB;	2003/06/19 13:52
			EPO; JPO; DERWENT	

				100000000000000000000000000000000000000
-	0	"6441487" and (gold)	USPAT;	2003/06/19
			US-PGPUB;	15:37
			EPO; JPO;	
	ا ہا	UE0241408 and /mold\	DERWENT USPAT;	2003/06/19
-	9	"5234149" and (gold)	US-PGPUB;	15:38
			EPO; JPO;	13.30
			DERWENT	
_	6	"5234149" and (under adj bump)	USPAT;	2003/06/19
		obolete and (animoleta) in the property of the	US-PGPUB;	19:18
			EPO; JPO;	
			DERWENT	
-	0	5234149.pn. and (under adj bump)	USPAT;	2003/06/19
			US-PGPUB;	17:48
			EPO; JPO;	
			DERWENT	2002/06/10
-	1	"20010011764" and (under adj bump)	USPAT;	2003/06/19
			US-PGPUB;	19:18
			EPO; JPO;	
		"20010011764" and (electroplating)	DERWENT USPAT;	2003/06/19
-	1	"20010011764" and (electropiating)	US-PGPUB;	19:19
			EPO; JPO;	
			DERWENT	
_	10	"5234149" and (reflow\$3)	USPAT;	2003/06/20
	1		US-PGPUB;	10:15
			EPO; JPO;	
	·		DERWENT	
_	0	5234149.pn. and (reflow\$3)	USPAT;	2003/06/20
		-	US-PGPUB;	10:16
			EPO; JPO;	
			DERWENT	0000/05/00
-	1	20010011764.pn. and (reflow\$3)	USPAT;	2003/06/20
			US-PGPUB;	10:31
			EPO; JPO; DERWENT	
1	1	20010011764.pn. and (lead)	USPAT;	2003/06/20
-	1	20010011764.pn. and (read)	US-PGPUB;	10:34
			EPO; JPO;	
			DERWENT	
_	1	20010011764.pn. and (reflow\$3)	USPAT;	2003/06/20
Ì		• • • • • • • • • • • • • • • • • • • •	US-PGPUB;	11:05
	-		EPO; JPO;	
			DERWENT	
-	0	20010011764.pn. and (selective adj	USPAT;	2003/06/20
		electroplating)	US-PGPUB;	11:05
	1		EPO; JPO;	
	1	(	DERWENT USPAT;	2003/07/07
-	126	(integrated adj circuit) and (contact adj pad) and (under adj bump adj region or	USPAI;	10:01
		layer) and (solder adj bonds) and (wire	EPO; JPO;	
		adj bonds) and (barrier adj region or	DERWENT	
		layer) and (passivation adj region or		
		layer)		
-	0	438/14,15,762,763.ccls. and (integrated	USPAT;	2003/10/29
		adj circuit) and (contact adj pad) and	US-PGPUB;	11:25
1	1	((under adj bump adj metallurgy) or ubm)	EPO; JPO;	
		and (solder) and (wire) and (barrier)	DERWENT	0000/07/07
-	32	(integrated adj circuit) and (contact adj	USPAT;	2003/07/07
		pad) and ((under adj bump adj metallurgy)	US-PGPUB;	10:03
		or ubm) and (solder) and (wire) and	EPO; JPO;	
i	1100	(barrier) and (lead)	DERWENT USPAT;	2003/10/28
-	1103	((bond adj pad) or terminal) near (copper	USPAT; US-PGPUB;	16:44
		or Cu)	EPO; JPO;	10.44
1			DERWENT	
_	545	((bond adj pad) or terminal) near (copper	USPAT;	2003/10/28
		or Cu) and ((wire adj bonding) or wire)	US-PGPUB;	16:46
1			EPO; JPO;	
1			DERWENT	
	<del></del>			

-	1	6133065.pn. and wire and solder	USPAT;	2003/12/02
			US-PGPUB;	18:10
			EPO; JPO;	
			DERWENT	/
-	. 0	6133065.pn. and wire and solder and	USPAT;	2003/10/29
		underbump	US-PGPUB;	11:59
			EPO; JPO;	
		5122055 1 lands	DERWENT	2003/10/29
-	0	6133065.pn. and underbump	USPAT; US-PGPUB;	12:09
			EPO; JPO;	12.09
			DERWENT	
	1 1	6335104.pn. and wire and solder	USPAT;	2003/10/29
-	*	0555104.pm. and wire and solder	US-PGPUB;	12:29
			EPO; JPO;	
			DERWENT	
<del>-</del>	2	4268849.pn.	USPAT;	2003/10/29
	_		US-PGPUB;	12:33
			EPO; JPO;	
	!		DERWENT	
_	0	4268849.pn. and wire and solder	USPAT;	2003/10/29
		-	US-PGPUB;	12:34
			EPO; JPO;	ļ
			DERWENT	
-	1	6335104.pn. and solder	USPAT;	2003/11/07
	ļ		US-PGPUB;	12:07
			EPO; JPO;	
			DERWENT	0000/11/07
-	1	20010011764.pn. and wire	USPAT;	2003/11/07
			US-PGPUB;	12:37
			EPO; JPO;	
		00010000745	DERWENT	2003/11/07
_	1	20010020745.pn. and wire	USPAT;	12:38
			US-PGPUB; EPO; JPO;	12.30
			DERWENT	İ
	1	20010020745.pn. and solder	USPAT;	2003/11/07
_	1	Z0010020743.pii. and S01del	US-PGPUB;	12:38
			EPO; JPO;	1
			DERWENT	
_	2	20020143830.pn.	USPAT;	2003/11/12
		•	US-PGPUB;	11:55
ļ		·	EPO; JPO;	
			DERWENT	
-	2	20030143830.pn.	USPAT;	2003/11/12
1			US-PGPUB;	11:55
			EPO; JPO;	
	_	1 33	DERWENT	2002/11/12
-	0	20030143830.pn. and solder	USPAT;	2003/11/12
			US-PGPUB; EPO; JPO;	11:57
			DERWENT	
_	2	20010011764.pn.	USPAT;	2003/11/12
-	"	20010011/04.pii.	US-PGPUB;	11:58
			EPO; JPO;	=
			DERWENT	
-	2	20010011764.pn.	USPAT;	2003/11/12
			US-PGPUB;	11:58
			EPO; JPO;	
			DERWENT	
-	1	20010011764.pn. and wire	USPAT;	2003/11/12
			US-PGPUB;	12:19
			EPO; JPO;	
			DERWENT	0000/11/10
-	1	20010011764.pn. and (reflow same solder)	USPAT;	2003/11/12
			US-PGPUB;	13:44
			EPO; JPO;	
		20010011764 nn and /mafless area and de-	DERWENT	2003/11/12
-	1	20010011764.pn. and (reflow same solder same diffusion)	USPAT; US-PGPUB;	13:47
		Same dillusion;	EPO; JPO;	13.37
1	l		DERWENT	j
1	1		1	1

		00010011764	TICDAM.	1 2002 /11 /12
-	1	20010011764.pn. and (reflow same solder	USPAT;	2003/11/12
		same (diffusion or diffus\$3))	US-PGPUB;	13:48
			EPO; JPO;	
	i		DERWENT	1
_	2	6133065.pn.	USPAT;	2003/11/17
			US-PGPUB;	07:48
			EPO; JPO;	
			DERWENT	
_	2	6335104.pn.	USPAT;	2003/11/17
		-	US-PGPUB;	07:50
	.		EPO; JPO;	
			DERWENT	
_	2	20010020745.pn.	USPAT;	2003/11/17
	-		US-PGPUB;	07:59
			EPO; JPO;	
			DERWENT	
_	2	6335104.pn.	USPAT;	2003/11/17
		0555104.pm.	US-PGPUB;	08:00
			EPO; JPO;	*****
	]		DERWENT	
	2	20030143830.pn.	USPAT;	2003/11/17
-		20030143630.pm.	US-PGPUB;	08:01
			EPO; JPO;	00.01
			DERWENT	
		20020107127	USPAT;	2003/11/17
-	2	20030107137.pn.		08:02
			US-PGPUB;	08:02
			EPO; JPO;	
			DERWENT	2002/11/17
-	2	20010011764.pn.	USPAT;	2003/11/17
			US-PGPUB;	08:04
			EPO; JPO;	
			DERWENT	0000/11/17
-	2	20010020745.pn.	USPAT;	2003/11/17
			US-PGPUB;	08:04
			EPO; JPO;	
			DERWENT	
_	2	6133065.pn.	USPAT;	2003/12/02
			US-PGPUB;	18:10
			EPO; JPO;	
			DERWENT	
_	2	20030143830.pn.	USPAT;	2003/12/02
		_	US-PGPUB;	18:26
			EPO; JPO;	
	1	I	DEDMENT	1